

## (12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization  
International Bureau



(43) International Publication Date  
17 May 2001 (17.05.2001)

PCT

(10) International Publication Number  
**WO 01/35704 A1**

(51) International Patent Classification<sup>7</sup>: H05K 3/40, 3/38

(21) International Application Number: PCT/US00/30015

(22) International Filing Date: 31 October 2000 (31.10.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
11/315106 5 November 1999 (05.11.1999) JP

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(81) Designated States (national): KR, SG, US.

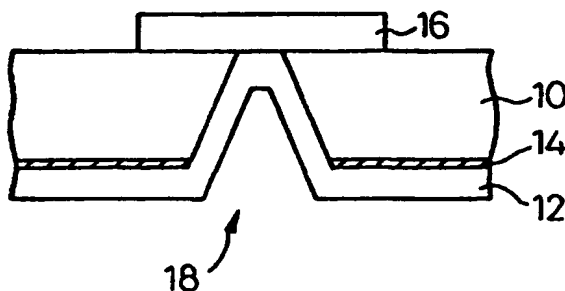
Published:

— With international search report.

For two-letter codes and other abbreviations, refer to the "Guid-  
ance Notes on Codes and Abbreviations" appearing at the begin-  
ning of each regular issue of the PCT Gazette.



(54) Title: MULTI-LAYER DOUBLE-SIDED WIRING BOARD AND METHOD OF FABRICATING THE SAME



(57) Abstract: The present invention provides a multi-layer double-sided wiring board which provides excellent adhesion between the conductive layer (12) and the insulating layer (10) because of the provision of an interface layer (14) therebetween, and which exhibits excellent conductivity reliability because the upper and lower conductive layers (16, 12) are joined together within the blind via (18) without interposing a dissimilar metal.

WO 01/35704 A1